

## PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Shih-Wei CHEN	02/26/2013
RECEIVING PARTY DATA	
Name:	TSMC Solar Ltd.
Street Address:	No. 5, Keya W. Road
Internal Address:	Daya District
City:	Taichung City
State/Country:	TAIWAN
Postal Code:	428-82
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13781920
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ATTORNEY DOCKET NUMBER:	2012.1324/1781.01133
NAME OF SUBMITTER:	Steven E. Koffs
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Serial No. 13/781,920  
filed March 1, 2013

**ATTORNEY DOCKET NO.: 2012.1324/1781.01133**

**ASSIGNMENT AND AGREEMENT**

For value received, I, **Shih-Wei CHEN**, hereby transfers to **TSMC Solar Ltd.**, with its principal place of business located at No. 5, Keya W. Road, Daya District, Taichung City 428-82, Taiwan, Republic of China, and its successors, assigns and legal representatives, the entire right, title and interest, for the United States of America, in and to certain inventions related to **METHOD OF FORMING A BUFFER LAYER IN A SOLAR CELL, AND A SOLAR CELL FORMED BY THE METHOD**, described in a non-provisional application claiming priority thereto and under any and all Letters Patent and any divisions, continuations, continuations-in-part, reexamination certificates, reissues, and extensions thereof, or claiming priority therefrom that may be granted in the United States for said inventions; and I also concurrently hereby sell, assign and transfer to **TSMC Solar Ltd.**, the entire right, title and interest in and to said inventions for all countries foreign to the United States, including all rights of priority arising from the application aforesaid, and all the rights and privileges under any and all forms of protection, including Letters Patent, that may be granted in said countries foreign to the United States for said inventions.

I authorize **TSMC Solar Ltd.** to make application for such protection in its own name and maintain such protection in any and all countries foreign to the United States, and to invoke and claim for any application for patent or other form of protection for said inventions, without further authorization from me, any and all benefits, including the right of priority provided by any and all treaties, conventions, or agreements.

I hereby consent that a copy of this assignment shall be deemed a full legal and formal equivalent of any document which may be required in any country in proof of the right of **TSMC Solar Ltd.** to apply for patent or other form of protection for said inventions and to claim the aforesaid benefit of the right of priority.

I request that any and all patents for said inventions be issued to **TSMC Solar Ltd.** in the United States and in all countries foreign to the United States, or to such nominees as **TSMC Solar Ltd.** may designate.

ATTORNEY DOCKET NO.: 2012.1324/1781.01133

I agree that, when requested, I shall, without charge to TSMC Solar Ltd. but at its expense, sign all papers, and do all acts which may be necessary, desirable or convenient in connection with said applications, patents, or other forms of protection.

Inventor No. 1

Dated: ✓ 2013/2/26

✓ Shih-wei CHEN  
Shih-Wei CHEN

Residence:

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